

MBRS320

Features

- Compact surface mount with J-bend leads (SMC)
- 3.0 Watt Power Dissipation package
- 3.0 Ampere, forward voltage less than 500 mV



SMC (D0-214AB) Color Band Denotes Cathode Mark: B32

Schottky Rectifier

Absolute Maximum Ratings*

T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Maximum Repetitive Reverse Voltage	20	V
I _{F(AV)}	Average Rectified Forward Current @ T _L = 100°C T _L = 90°C	3.0 4.0	A A
I _{FSM}	Non-repetitive Peak Forward Surge Current (Half wave, single phase, 60 Hz)	80	A
T _{stg}	Storage Temperature Range	-65 to +150	°C
T _j	Operating Junction Temperature	-65 to +125	°C

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JL}$	Thermal Resistance, Junction to Lead	11	°C/W

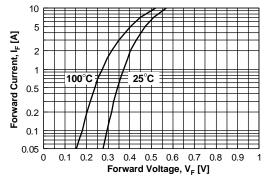
Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol		Value	Units	
V _F	Forward Voltage	@ I _F = 3.0A,	500	mV
I _R	Reverse Current	@ V _R = 20 V, V _R = 20 V, T _A = 100 °C	2.0 20	mA mA

Schottky Rectifier

(continued)

Typical Characteristics



0.001 0 2 4 6 8 10 12 14 16 18 20 Reverse Voltage, V_R[V]

Figure 1. Forward Voltage Characteristics

Figure 2. Reverse Current vs Reverse Voltage

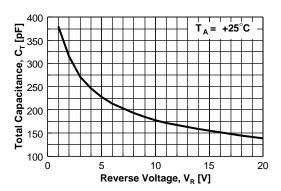


Figure 3. Total Capacitance

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